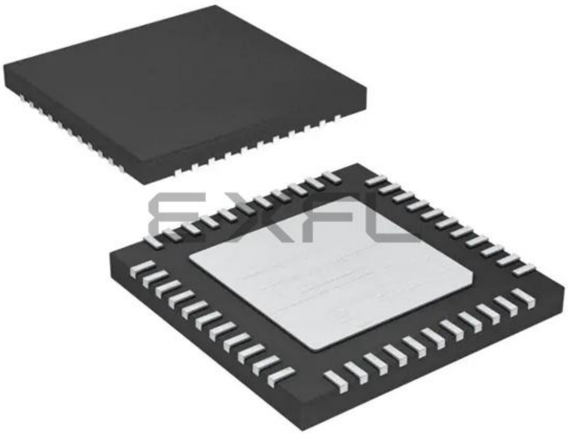
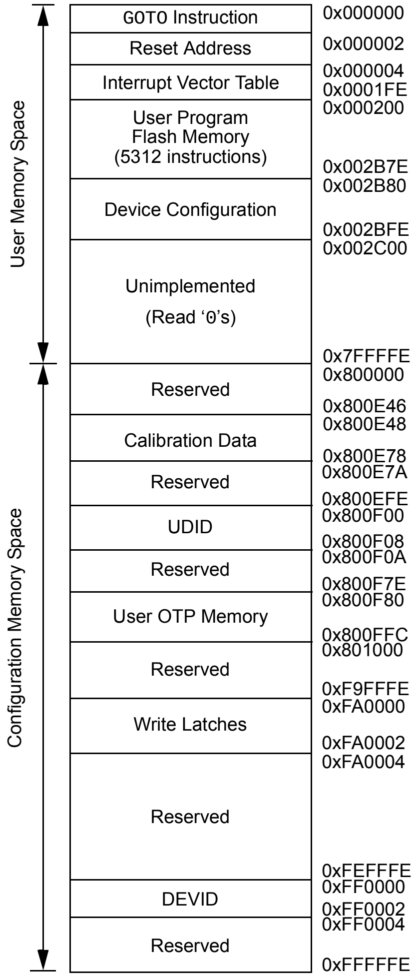
Microchip Technology - DSPIC33EP64GS504T-E/ML Datasheet



Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	35
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 19x12b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep64gs504t-e-ml

FIGURE 4-1: PROGRAM MEMORY MAP FOR dsPIC33EP16GS50X DEVICES



Note: Memory areas are not shown to scale.

5.4 Dual Partition Flash Configuration

For dsPIC33EP64GS50X devices operating in Dual Partition Flash Program Memory modes, the Inactive Partition can be erased and programmed without stalling the processor. The same programming algorithms are used for programming and erasing the Flash in the Inactive Partition, as described in **Section 5.2 "RTSP Operation"**. On top of the page erase option, the entire Flash memory of the Inactive Partition can be erased by configuring the NVMOP<3:0> bits in the NVMCON register.

> **Note 1:** The application software to be loaded into the Inactive Partition will have the address of the Active Partition. The bootloader firmware will need to offset the address by 0x400000 in order to write to the Inactive Partition.

5.4.1 FLASH PARTITION SWAPPING

The Boot Sequence Number is used for determining the Active Partition at start-up and is encoded within the FBTSEQ Configuration register bits. Unlike most Configuration registers, which only utilize the lower 16 bits of the program memory, FBTSEQ is a 24-bit Configuration Word. The Boot Sequence Number (BSEQ) is a 12-bit value and is stored in FBTSEQ twice. The true value is stored in bits, FBTSEQ<11:0>, and its complement is stored in bits, FBTSEQ<23:12>. At device Reset, the sequence numbers are read and the partition with the lowest sequence number becomes the Active Partition. If one of the Boot Sequence Numbers is invalid, the device will select the partition with the valid Boot Sequence Number, or default to Partition 1 if both sequence numbers are invalid. See **Section 23.0 "Special Features"** for more information.

The `BOOTSWP` instruction provides an alternative means of swapping the Active and Inactive Partitions (soft swap) without the need for a device Reset. The `BOOTSWP` must always be followed by a `GOTO` instruction. The `BOOTSWP` instruction swaps the Active and Inactive Partitions, and the PC vectors to the location specified by the `GOTO` instruction in the newly Active Partition.

It is important to note that interrupts should temporarily be disabled while performing the soft swap sequence and that after the partition swap, all peripherals and interrupts which were enabled remain enabled. Additionally, the RAM and stack will maintain state after the switch. As a result, it is recommended that applications using soft swaps jump to a routine that will reinitialize the device in order to ensure the firmware runs as expected. The Configuration registers will have no effect during a soft swap.

For robustness of operation, in order to execute the `BOOTSWP` instruction, it is necessary to execute the NVM unlocking sequence as follows:

1. Write 0x55 to NVMKEY.
2. Write 0xAA to NVMKEY.
3. Execute the `BOOTSWP` instruction.

If the unlocking sequence is not performed, the `BOOTSWP` instruction will be executed as a forced `NOP` and a `GOTO` instruction, following the `BOOTSWP` instruction, will be executed, causing the PC to jump to that location in the current operating partition.

The SFTSWP and P2ACTIV bits in the NVMCON register are used to determine a successful swap of the Active and Inactive Partitions, as well as which partition is active. After the `BOOTSWP` and `GOTO` instructions, the SFTSWP bit should be polled to verify the partition swap has occurred and then cleared for the next panel swap event.

5.4.2 DUAL PARTITION MODES

While operating in Dual Partition mode, dsPIC33EP64GS50X family devices have the option for both partitions to have their own defined security segments, as shown in Figure 23-4. Alternatively, the device can operate in Protected Dual Partition mode, where Partition 1 becomes permanently erase/write-protected. Protected Dual Partition mode allows for a "Factory Default" mode, which provides a fail-safe backup image to be stored in Partition 1.

dsPIC33EP64GS50X family devices can also operate in Privileged Dual Partition mode, where additional security protections are implemented to allow for protection of intellectual property when multiple parties have software within the device. In Privileged Dual Partition mode, both partitions place additional restrictions on the BSLIM register. These prevent changes to the size of the Boot Segment and General Segment, ensuring that neither segment will be altered.

5.5 Flash Memory Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page contains the latest updates and additional information.

5.5.1 KEY RESOURCES

- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

5.6 Control Registers

Five SFRs are used to write and erase the program Flash memory: NVMCON, NVMKEY, NVMADR, NVMADRU and NVMSRCADR/H.

The NVMCON register (Register 5-1) selects the operation to be performed (page erase, word/row program, Inactive Partition erase), initiates the program or erase cycle and is used to determine the Active Partition in Dual Partition modes.

NVMKEY (Register 5-4) is a write-only register that is used for write protection. To start a programming or erase sequence, the user application must consecutively write 0x55 and 0xAA to the NVMKEY register.

There are two NVM Address registers: NVMADRU and NVMADR. These two registers, when concatenated, form the 24-bit Effective Address (EA) of the selected word/row for programming operations, or the selected page for erase operations. The NVMADRU register is used to hold the upper 8 bits of the EA, while the NVMADR register is used to hold the lower 16 bits of the EA.

For row programming operation, data to be written to program Flash memory is written into data memory space (RAM) at an address defined by the NVMSRCADR register (location of first element in row programming data).

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1 (CONTINUED)

bit 2	**STKERR:** Stack Error Trap Status bit `1` = Stack error trap has occurred `0` = Stack error trap has not occurred
bit 1	**OSCFAIL:** Oscillator Failure Trap Status bit `1` = Oscillator failure trap has occurred `0` = Oscillator failure trap has not occurred
bit 0	**Unimplemented:** Read as ‘`0`’

REGISTER 10-11: RPINR19: PERIPHERAL PIN SELECT INPUT REGISTER 19

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
U2CTSR7	U2CTSR6	U2CTSR5	U2CTSR4	U2CTSR3	U2CTSR2	U2CTSR1	U2CTSR0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
U2RXR7	U2RXR6	U2RXR5	U2RXR4	U2RXR3	U2RXR2	U2RXR1	U2RXR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **U2CTSR<7:0>:** Assign UART2 Clear-to-Send ($\overline{\text{U2CTS}}$) to the Corresponding RPn Pin bits

`10110101` = Input tied to RP181
`10110100` = Input tied to RP180
•
•
•
`00000001` = Input tied to RP1
`00000000` = Input tied to VSS

bit 7-0 **U2RXR<7:0>:** Assign UART2 Receive (U2RX) to the Corresponding RPn Pin bits

`10110101` = Input tied to RP181
`10110100` = Input tied to RP180
•
•
•
`00000001` = Input tied to RP1
`00000000` = Input tied to VSS

REGISTER 10-12: RPINR20: PERIPHERAL PIN SELECT INPUT REGISTER 20

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SCK1INR7	SCK1INR6	SCK1INR5	SCK1INR4	SCK1INR3	SCK1INR2	SCK1INR1	SCK1INR0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SDI1R7	SDI1R6	SDI1R5	SDI1R4	SDI1R3	SDI1R2	SDI1R1	SDI1R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **SCK1INR<7:0>:** Assign SPI1 Clock Input (SCK1) to the Corresponding RPn Pin bits

`10110101` = Input tied to RP181
`10110100` = Input tied to RP180
•
•
•
`00000001` = Input tied to RP1
`00000000` = Input tied to VSS

bit 7-0 **SDI1R<7:0>:** Assign SPI1 Data Input (SDI1) to the Corresponding RPn Pin bits

`10110101` = Input tied to RP181
`10110100` = Input tied to RP180
•
•
•
`00000001` = Input tied to RP1
`00000000` = Input tied to VSS

REGISTER 10-22: RPOR2: PERIPHERAL PIN SELECT OUTPUT REGISTER 2

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP37R5	RP37R4	RP37R3	RP37R2	RP37R1	RP37R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP36R5	RP36R4	RP36R3	RP36R2	RP36R1	RP36R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14	**Unimplemented:** Read as ‘0’
bit 13-8	**RP37R<5:0>:** Peripheral Output Function is Assigned to RP37 Output Pin bits (see Table 10-2 for peripheral function numbers)
bit 7-6	**Unimplemented:** Read as ‘0’
bit 5-0	**RP36R<5:0>:** Peripheral Output Function is Assigned to RP36 Output Pin bits (see Table 10-2 for peripheral function numbers)

REGISTER 10-23: RPOR3: PERIPHERAL PIN SELECT OUTPUT REGISTER 3

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP39R5	RP39R4	RP39R3	RP39R2	RP39R1	RP39R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP38R5	RP38R4	RP38R3	RP38R2	RP38R1	RP38R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14	**Unimplemented:** Read as ‘0’
bit 13-8	**RP39R<5:0>:** Peripheral Output Function is Assigned to RP39 Output Pin bits (see Table 10-2 for peripheral function numbers)
bit 7-6	**Unimplemented:** Read as ‘0’
bit 5-0	**RP38R<5:0>:** Peripheral Output Function is Assigned to RP38 Output Pin bits (see Table 10-2 for peripheral function numbers)

REGISTER 10-30: RPOR10: PERIPHERAL PIN SELECT OUTPUT REGISTER 10

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP53R5	RP53R4	RP53R3	RP53R2	RP53R1	RP53R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP52R5	RP52R4	RP52R3	RP52R2	RP52R1	RP52R0
bit 7							bit 0

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14	**Unimplemented:** Read as ‘0’
bit 13-8	**RP53R<5:0>:** Peripheral Output Function is Assigned to RP53 Output Pin bits (see Table 10-2 for peripheral function numbers)
bit 7-6	**Unimplemented:** Read as ‘0’
bit 5-0	**RP52R<5:0>:** Peripheral Output Function is Assigned to RP52 Output Pin bits (see Table 10-2 for peripheral function numbers)

REGISTER 10-31: RPOR11: PERIPHERAL PIN SELECT OUTPUT REGISTER 11

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP55R5	RP55R4	RP55R3	RP55R2	RP55R1	RP55R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP54R5	RP54R4	RP54R3	RP54R2	RP54R1	RP54R0
bit 7							bit 0

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14	**Unimplemented:** Read as ‘0’
bit 13-8	**RP55R<5:0>:** Peripheral Output Function is Assigned to RP55 Output Pin bits (see Table 10-2 for peripheral function numbers)
bit 7-6	**Unimplemented:** Read as ‘0’
bit 5-0	**RP54R<5:0>:** Peripheral Output Function is Assigned to RP54 Output Pin bits (see Table 10-2 for peripheral function numbers)

REGISTER 16-2: SPIxCON1: SPIx CONTROL REGISTER 1

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	DISSCK	DISSDO	MODE16	SMP	CKE(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SSEN(2)	CKP	MSTEN	SPRE2(3)	SPRE1(3)	SPRE0(3)	PPRE1(3)	PPRE0(3)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘`0`’

bit 12 **DISSCK:** Disable SCKx Pin bit (SPIx Master modes only)
`1` = Internal SPIx clock is disabled, pin functions as I/O
`0` = Internal SPIx clock is enabled

bit 11 **DISSDO:** Disable SDOx Pin bit
`1` = SDOx pin is not used by the module; pin functions as I/O
`0` = SDOx pin is controlled by the module

bit 10 **MODE16:** Word/Byte Communication Select bit
`1` = Communication is word-wide (16 bits)
`0` = Communication is byte-wide (8 bits)

bit 9 **SMP:** SPIx Data Input Sample Phase bit
Master Mode:
`1` = Input data is sampled at the end of data output time
`0` = Input data is sampled at the middle of data output time
Slave Mode:
SMP must be cleared when SPIx is used in Slave mode.

bit 8 **CKE:** SPIx Clock Edge Select bit(1)
`1` = Serial output data changes on transition from active clock state to Idle clock state (refer to bit 6)
`0` = Serial output data changes on transition from Idle clock state to active clock state (refer to bit 6)

bit 7 **SSEN:** Slave Select Enable bit (Slave mode)(2)
`1` = $\overline{\text{SSx}}$ pin is used for Slave mode
`0` = $\overline{\text{SSx}}$ pin is not used by the module; pin is controlled by port function

bit 6 **CKP:** Clock Polarity Select bit
`1` = Idle state for clock is a high level; active state is a low level
`0` = Idle state for clock is a low level; active state is a high level

bit 5 **MSTEN:** Master Mode Enable bit
`1` = Master mode
`0` = Slave mode

Note 1: The CKE bit is not used in Framed SPI modes. Program this bit to ‘`0`’ for Framed SPI modes (FRMEN = `1`).
2: This bit must be cleared when FRMEN = `1`.
3: Do not set both primary and secondary prescalers to the value of 1:1.

REGISTER 19-26: ADTRIGxL: ADC CHANNEL TRIGGER x SELECTION REGISTER LOW (x = 0 to 5) (CONTINUED)

bit 4-0	**TRGSRC(4x)<4:0>:** Trigger Source Selection for Corresponding Analog Inputs bits `11111` = ADTRG31 `11110` = Reserved `11101` = Reserved `11100` = PWM Generator 5 current-limit trigger `11011` = PWM Generator 4 current-limit trigger `11010` = PWM Generator 3 current-limit trigger `11001` = PWM Generator 2 current-limit trigger `11000` = PWM Generator 1 current-limit trigger `10111` = Output Compare 2 trigger `10110` = Output Compare 1 trigger `10101` = Reserved `10100` = Reserved `10011` = PWM Generator 5 secondary trigger `10010` = PWM Generator 4 secondary trigger `10001` = PWM Generator 3 secondary trigger `10000` = PWM Generator 2 secondary trigger `01111` = PWM Generator 1 secondary trigger `01110` = PWM secondary Special Event Trigger `01101` = Timer2 period match `01100` = Timer1 period match `01011` = Reserved `01010` = Reserved `01001` = PWM Generator 5 primary trigger `01000` = PWM Generator 4 primary trigger `00111` = PWM Generator 3 primary trigger `00110` = PWM Generator 2 primary trigger `00101` = PWM Generator 1 primary trigger `00100` = PWM Special Event Trigger `00011` = Reserved `00010` = Level software trigger `00001` = Common software trigger `00000` = No trigger is enabled

REGISTER 19-30: ADCAL1H: ADC CALIBRATION REGISTER 1 HIGH

R/W-0, HS	U-0	U-0	U-0	r-0	R/W-0	R/W-0	R/W-0
CSHRRDY	—	—	—	—	CSHRDIFF	CSHREN	CSHRRUN
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:	r = Reserved bit	U = Unimplemented bit, read as ‘0’	
R = Readable bit	W = Writable bit	HS = Hardware Settable bit	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**CSHRRDY:** Shared ADC Core Calibration Status Flag bit `1` = Shared ADC core calibration is finished `0` = Shared ADC core calibration is in progress
bit 14-12	**Unimplemented:** Read as ‘`0`’
bit 11	**Reserved:** Must be written as ‘`0`’
bit 10	**CSHRDIFF:** Shared ADC Core Differential-Mode Calibration bit `1` = Shared ADC core will be calibrated in Differential Input mode `0` = Shared ADC core will be calibrated in Single-Ended Input mode
bit 9	**CSHREN:** Shared ADC Core Calibration Enable bit `1` = Shared ADC core calibration bits (CSHRRDY, CSHRDIFF and CSHRRUN) can be accessed by software `0` = Shared ADC core calibration bits are disabled
bit 8	**CSHRRUN:** Shared ADC Core Calibration Start bit `1` = If this bit is set by software, the shared ADC core calibration cycle is started; this bit is cleared automatically by hardware `0` = Software can start the next calibration cycle
bit 7-0	**Unimplemented:** Read as ‘`0`’

REGISTER 19-31: ADCMPxCON: ADC DIGITAL COMPARATOR x CONTROL REGISTER (x = 0 or 1)

U-0	U-0	U-0	R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC
—	—	—	CHNL4	CHNL3	CHNL2	CHNL1	CHNL0
bit 15							bit 8

R/W-0	R/W-0	R-0, HC, HS	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CMPEN	IE	STAT	BTWN	HIHI	HILO	LOHI	LOLO
bit 7							bit 0

Legend:	HC = Hardware Clearable bit	U = Unimplemented bit, read as ‘0’	
R = Readable bit	W = Writable bit	HSC = Hardware Settable/Clearable bit	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	HS = Hardware Settable bit

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12-8 **CHNL<4:0>:** Input Channel Number bits

If the comparator has detected an event for a channel, this channel number is written to these bits.
11111 = Reserved
•
•
10110 = Reserved
10101 = AN21
10100 = AN20
•
•
00001 = AN1
00000 = AN0

bit 7 **CMPEN:** Comparator Enable bit

1 = Comparator is enabled
0 = Comparator is disabled and the STAT status bit is cleared

bit 6 **IE:** Comparator Common ADC Interrupt Enable bit

1 = Common ADC interrupt will be generated if the comparator detects a comparison event
0 = Common ADC interrupt will not be generated for the comparator

bit 5 **STAT:** Comparator Event Status bit

This bit is cleared by hardware when the channel number is read from the CHNL<4:0> bits.
1 = A comparison event has been detected since the last read of the CHNL<4:0> bits
0 = A comparison event has not been detected since the last read of the CHNL<4:0> bits

bit 4 **BTWN:** Between Low/High Comparator Event bit

1 = Generates a comparator event when ADCMPxLO ≤ ADCBUFx < ADCMPxHI
0 = Does not generate a digital comparator event when ADCMPxLO ≤ ADCBUFx < ADCMPxHI

bit 3 **HIHI:** High/High Comparator Event bit

1 = Generates a digital comparator event when ADCBUFx ≥ ADCMPxHI
0 = Does not generate a digital comparator event when ADCBUFx ≥ ADCMPxHI

bit 2 **HILO:** High/Low Comparator Event bit

1 = Generates a digital comparator event when ADCBUFx < ADCMPxHI
0 = Does not generate a digital comparator event when ADCBUFx < ADCMPxHI

bit 1 **LOHI:** Low/High Comparator Event bit

1 = Generates a digital comparator event when ADCBUFx ≥ ADCMPxLO
0 = Does not generate a digital comparator event when ADCBUFx ≥ ADCMPxLO

bit 0 **LOLO:** Low/Low Comparator Event bit

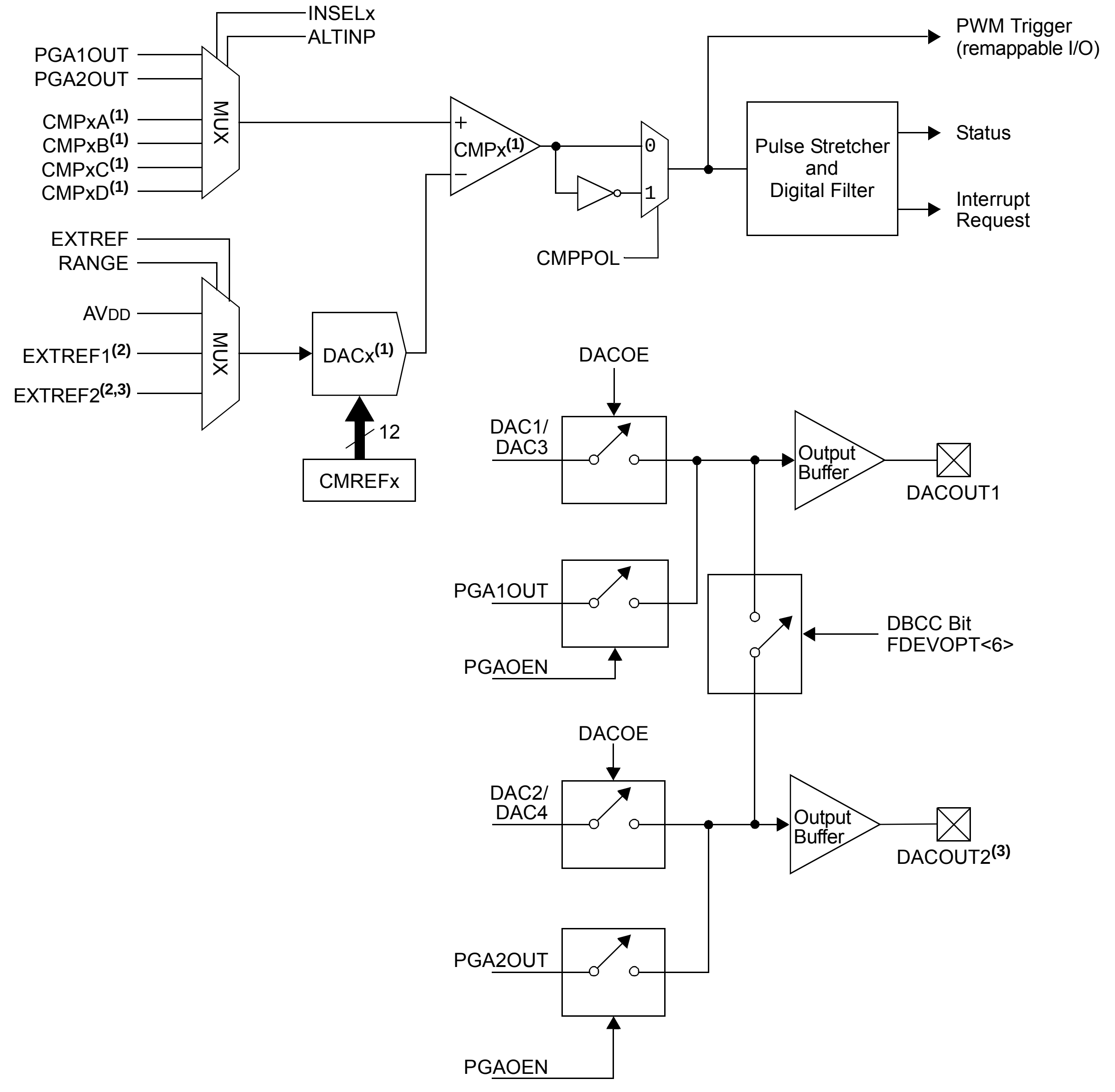
1 = Generates a digital comparator event when ADCBUFx < ADCMPxLO
0 = Does not generate a digital comparator event when ADCBUFx < ADCMPxLO

20.2 Module Description

Figure 20-1 shows a functional block diagram of one analog comparator from the high-speed analog comparator module. The analog comparator provides high-speed operation with a typical delay of 15 ns. The negative input of the comparator is always connected to the DACx circuit. The positive input of the comparator is connected to an analog multiplexer that selects the desired source pin.

The analog comparator input pins are typically shared with pins used by the Analog-to-Digital Converter (ADC) module. Both the comparator and the ADC can use the same pins at the same time. This capability enables a user to measure an input voltage with the ADC and detect voltage transients with the comparator.

FIGURE 20-1: HIGH-SPEED ANALOG COMPARATOR x MODULE BLOCK DIAGRAM



Note 1: x = 1-4

2: EXTREF1 is connected to DAC1/DAC3. EXTREF2 is connected to DAC2/DAC4.

3: Not available on all devices.

21.1 Module Description

The Programmable Gain Amplifiers are used to amplify small voltages (i.e., voltages across burden/shunt resistors) to improve the signal-to-noise ratio of the measured signal. The PGAx output voltage can be read by any of the four dedicated Sample-and-Hold circuits on the ADC module. The output voltage can also be fed to the comparator module for overcurrent/voltage protection. Figure 21-2 shows a functional block diagram of the PGAx module. Refer to **Section 19.0 “High-Speed, 12-Bit Analog-to-Digital Converter (ADC)”** and **Section 20.0 “High-Speed Analog Comparator”** for more interconnection details.

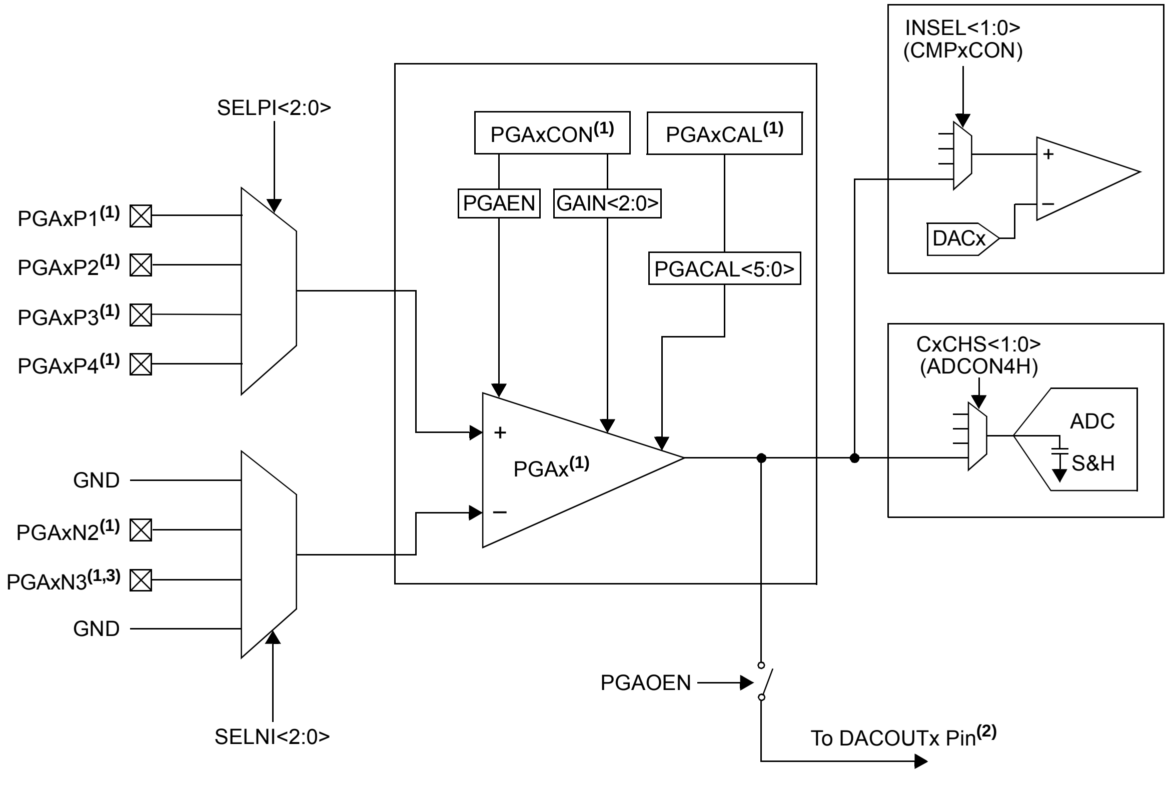
The gain of the PGAx module is selectable via the GAIN<2:0> bits in the PGAxCON register. There are five selectable gains, ranging from 4x to 64x. The SELPI<2:0> and SELNI<2:0> bits in the PGAxCON register select one of four positive/negative inputs to the PGAx module. For single-ended applications, the SELNI<2:0> bits will select the ground as the negative input source. To provide an independent ground reference, PGAxN2 and PGAxN3 pins are available as the negative input source to the PGAx module.

Note 1: Not all PGA positive/negative inputs are available on all devices. Refer to the specific device pinout for available input source pins.

The output voltage of the PGAx module can be connected to the DACOUTx pin by setting the PGAOEN bit in the PGAxCON register. When the PGAOEN bit is enabled, the output voltage of PGA1 is connected to DACOUT1 and PGA2 is connected to DACOUT2. For devices with a single DACOUTx pin, the output voltage of PGA2 can be connected to DACOUT1 by configuring the DBCC Configuration bit in the FDEVOPT register (FDEVOPT<6>).

If both the DACx output voltage and PGAx output voltage are connected to the DACOUTx pin, the resulting output voltage would be a combination of signals. There is no assigned priority between the PGAx module and the DACx module.

FIGURE 21-2: PGAx FUNCTIONAL BLOCK DIAGRAM



Note 1: x = 1 and 2.
2: The DACOUT2 device pin is only available on 64-pin devices.
3: The PGAxN3 input is not available on 28-pin devices.

TABLE 26-14: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**[1]	**Max.**	**Units**	**Conditions**
		Program Flash Memory					
D130	E_P	Cell Endurance	10,000	—	—	E/W	-40°C to +125°C
D131	V_{PR}	V_{DD} for Read	3.0	—	3.6	V	
D132b	V_{PEW}	V_{DD} for Self-Timed Write	3.0	—	3.6	V	
D134	T_{RETD}	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated, -40°C to +125°C
D135	I_{DDP}	Supply Current during Programming[2]	—	10	—	mA	
D136	I_{PEAK}	Instantaneous Peak Current During Start-up	—	—	150	mA	
D137a	T_{PE}	Page Erase Time	19.7	—	20.1	ms	T_{PE} = 146893 FRC cycles, T_A = +85°C **(Note 3)**
D137b	T_{PE}	Page Erase Time	19.5	—	20.3	ms	T_{PE} = 146893 FRC cycles, T_A = +125°C **(Note 3)**
D138a	T_{WW}	Word Write Cycle Time	46.5	—	47.3	µs	T_{WW} = 346 FRC cycles, T_A = +85°C **(Note 3)**
D138b	T_{WW}	Word Write Cycle Time	46.0	—	47.9	µs	T_{WW} = 346 FRC cycles, T_A = +125°C **(Note 3)**
D139a	T_{RW}	Row Write Time	667	—	679	µs	T_{RW} = 4965 FRC cycles, T_A = +85°C **(Note 3)**
D139b	T_{RW}	Row Write Time	660	—	687	µs	T_{RW} = 4965 FRC cycles, T_A = +125°C **(Note 3)**

Note 1: Data in "Typ." column is at 3.3V, +25°C unless otherwise stated.

2: Parameter characterized but not tested in manufacturing.

3: Other conditions: FRC = 7.37 MHz, TUN<5:0> = `011111` (for Minimum), TUN<5:0> = `100000` (for Maximum). This parameter depends on the FRC accuracy (see Table 26-20) and the value of the FRC Oscillator Tuning register (see Register 8-4). For complete details on calculating the Minimum and Maximum time, see **Section 5.3 "Programming Operations"**.

FIGURE 26-9: HIGH-SPEED PWMx MODULE FAULT TIMING CHARACTERISTICS

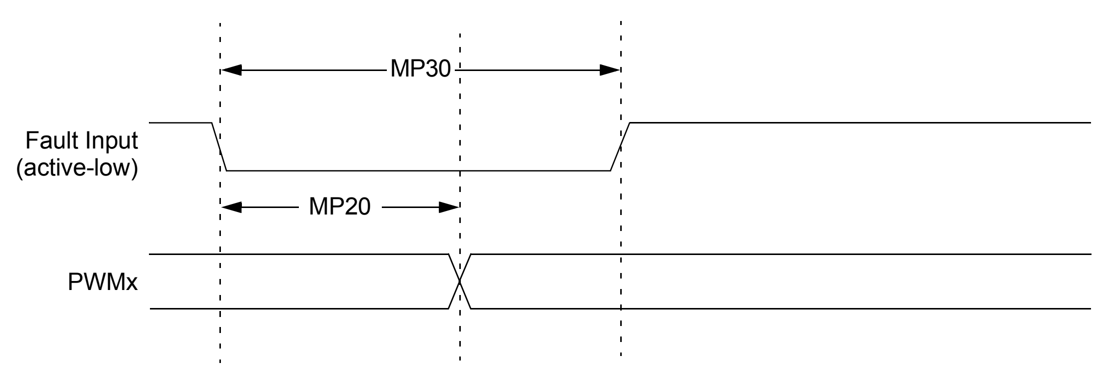
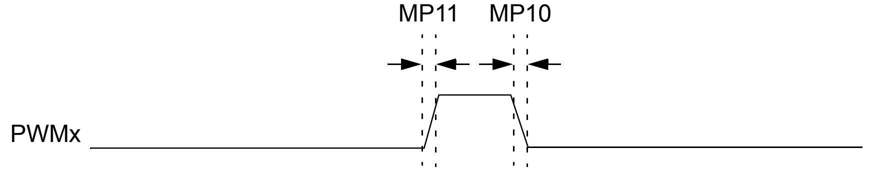


FIGURE 26-10: HIGH-SPEED PWMx MODULE TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-30: HIGH-SPEED PWMx MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
MP10	TFPWM	PWMx Output Fall Time	—	—	—	ns	See Parameter DO32
MP11	TRPWM	PWMx Output Rise Time	—	—	—	ns	See Parameter DO31
MP20	TFD	Fault Input ↓ to PWMx I/O Change	—	—	15	ns	
MP30	TFH	Fault Input Pulse Width	15	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 26-36: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCKx Input Frequency	—	—	Lesser of: F_P or 11	MHz	**(Note 3)**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid After SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SSx}}$ ↓ to SCKx ↑ or SCKx ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SSx}}$ ↑ to SDOx Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{\text{SSx}}$ ↑ after SCKx Edge	1.5 T_{CY} + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	SDOx Data Output Valid after $\overline{\text{SSx}}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

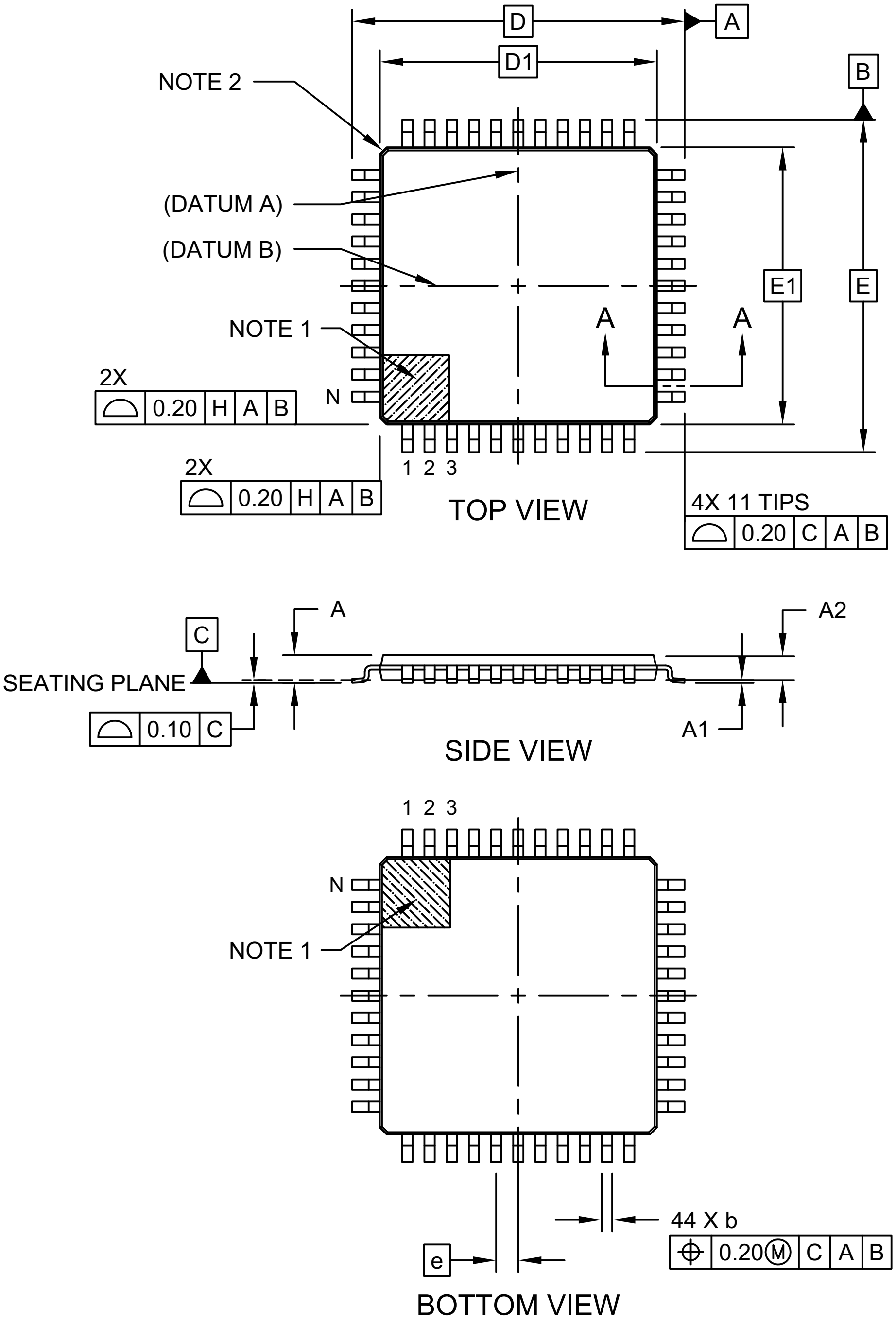
2: Data in "Typ." column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 91 ns. Therefore, the SCKx clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

44-Lead Plastic Thin Quad Flatpack (PT) - 10x10x1.0 mm Body [TQFP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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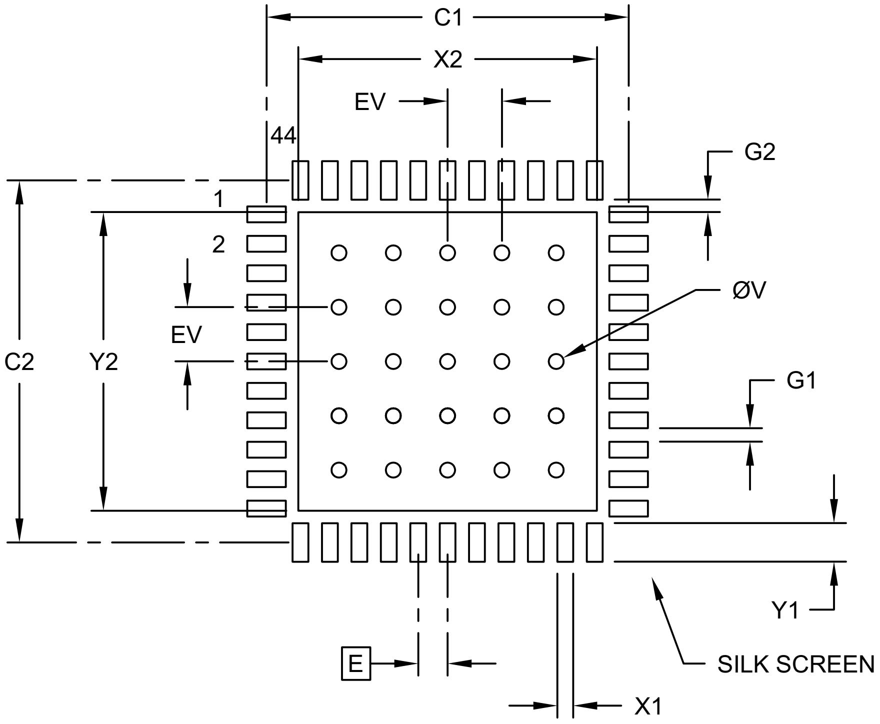
44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN or VQFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	X2			6.60
Optional Center Pad Length	Y2			6.60
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.85
Contact Pad to Contact Pad (X40)	G1	0.30		
Contact Pad to Center Pad (X44)	G2	0.28		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing No. C04-2103C

NOTES: